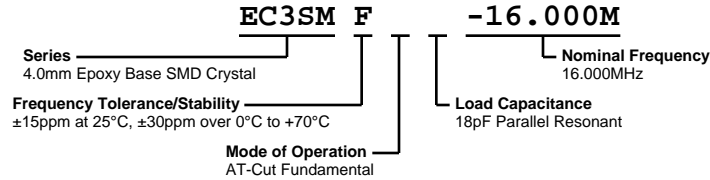


EC3SMF-16.000M



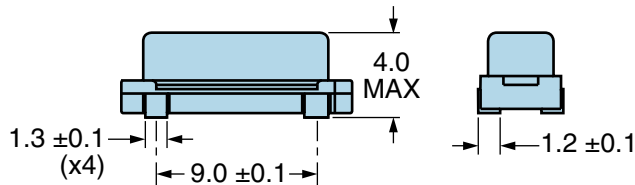
ELECTRICAL SPECIFICATIONS

Nominal Frequency	16.000MHz
Frequency Tolerance/Stability	$\pm 15\text{ppm}$ at 25°C , $\pm 30\text{ppm}$ over 0°C to $+70^\circ\text{C}$
Aging at 25°C	$\pm 5\text{ppm}/\text{year}$ Maximum
Load Capacitance	18pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	50 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	1mWatts Maximum
Storage Temperature Range	-40°C to $+85^\circ\text{C}$
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Crystal
2	Connected to Pin 3
3	Connected to Pin 2
4	Crystal

LINE	MARKING
1	E16.000 E=Ecliptek Designator

EC3SMF-16.000M

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ± 0.1

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 225°C

T_s MAX to T_L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T_L to T_p)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T _L)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T_p)	225°C Maximum
Target Peak Temperature (T_p Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (t_p)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.